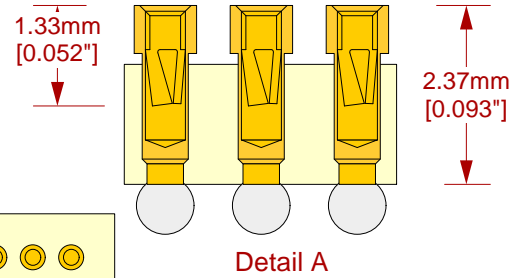
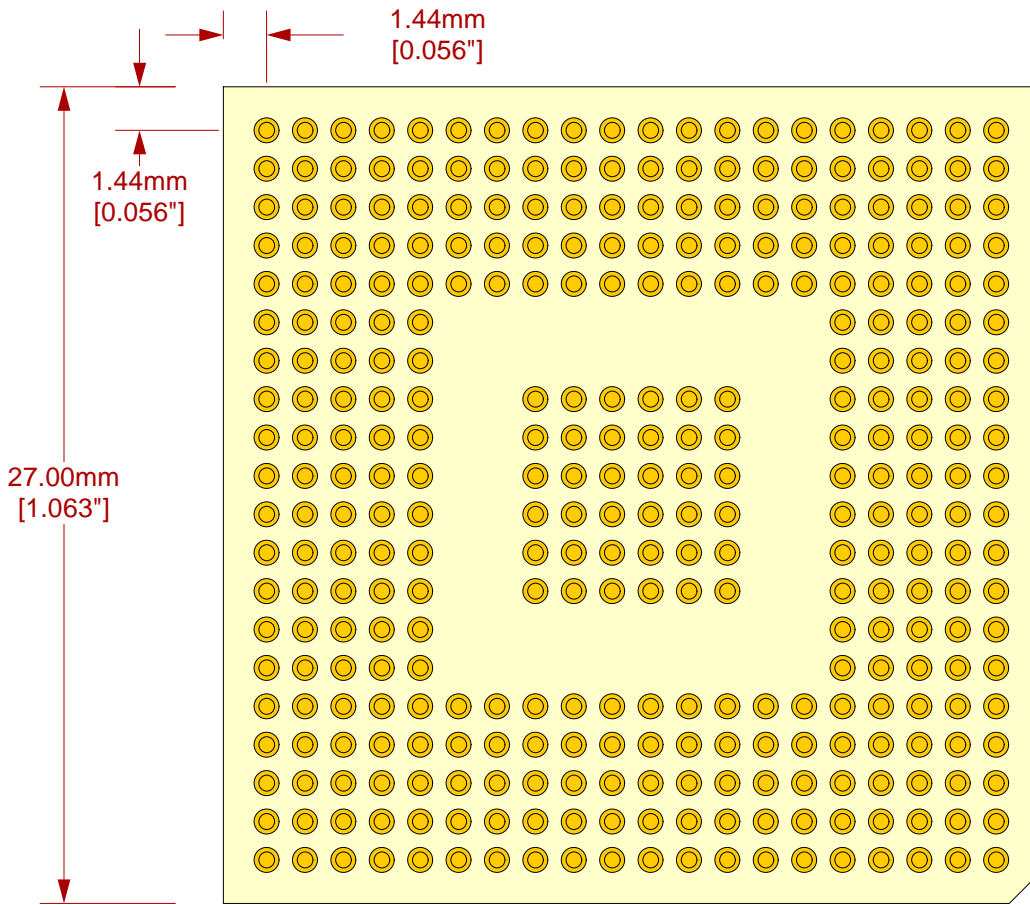
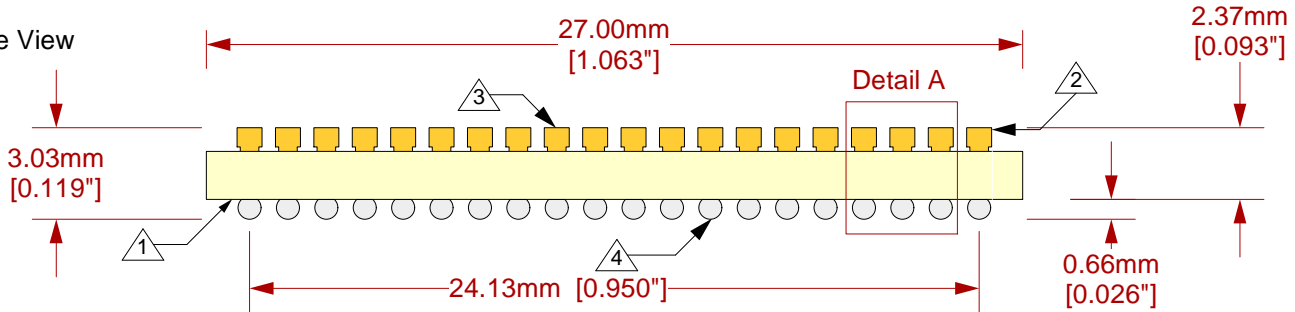


Patent Pending

Top View



Side View



CONTACT DATA


Accepts 0.20mm - 0.33mm Diameter pins
 3-finger
 37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)
 30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)
 20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)

- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ④ Balls: Eutectic 63/37 SnPb.

Description: Giga-snaP BGA SMT Foot

336 position (1.27mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SF-BGA336B-B-32 Drawing	Status: Released	Scale: 4:1	Rev: A
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: M.A.Fedde	Date: 12/23/05	
		File: SF-BGA336B-B-32 Dwg	Modified:	